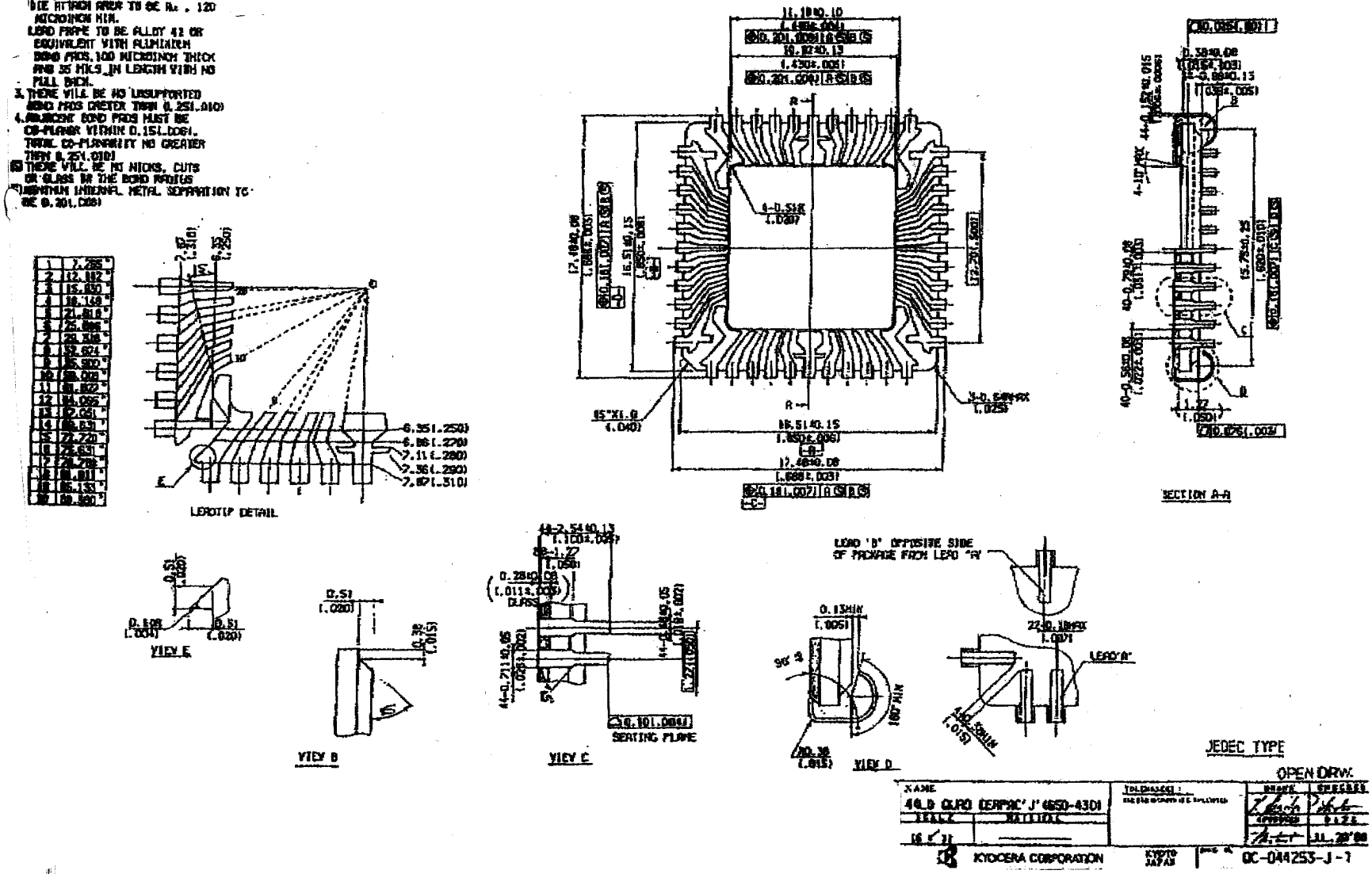
SSM P/N CQJ04421

NOTES
1. MATERIALS:
   CERAMIC TO OPAQUE, 90-94% Al_2O_3
   SOLDER GLASS TO BE 7585.
   MAX PULLBACK TO BE 0.25(.010)
   FROM CERAMIC EDGE.
   DIE ATTACH AREA TO BE Ra . 120
   MICROINCH MIN.
   LEAD FRAME TO BE ALLOY 42 OR
   EQUIVALENT WITH ALUMINUM
   BOND PADS, 100 MICROINCH THICK
   AND 35 MILS IN LENGTH WITH NO
   PULL BACK.
3. THERE WILL BE NO UNSUPPORTED
   BOND PADS GREATER THAN 0.25(.010)
4. ADJACENT BOND PADS MUST BE
   CO-PLANAR WITHIN 0.15(.006).
   TOTAL CO-PLANARITY NO GREATER
   THAN 0.25(.010)
5. THERE WILL BE NO NICKS, CUTS
   OR GLASS IN THE BOND RADIUS
6. MINIMUM INTERNAL METAL SEPARATION TO
   BE 0.20(.008)



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